FIBRE CHANNEL AND GIGABIT ETHERNET TRANSCEIVER S2052

FEATURES

- Functionally compliant with ANSI X3T11 Fibre Channel physical and transmission protocol standards and IEEE 802.3Z Gigabit Ethernet Applications
- Transmitter incorporates phase-locked loop (PLL) providing clock synthesis from low-speed reference
- Receiver PLL configured for clock and data recovery
- 1250 and 1062 Mb/s operation
- 10-bit parallel TTL compatible interface
- 800mW typical power dissipation
- +3.3V power supply
- Low-jitter serial PECL compatible interface
- Lock detect
- Local loopback
- 64 PQFP package
- Fibre Channel framing performed by receiver
- Continuous downstream clocking from receiver
- Drives 30m of Twinax cable directly

APPLICATIONS

High-speed data communications

- Workstation
- Frame buffer
- Switched networks
- Data broadcast environments
- Proprietary extended backplanes
- RAID drives
- Mass storage devices

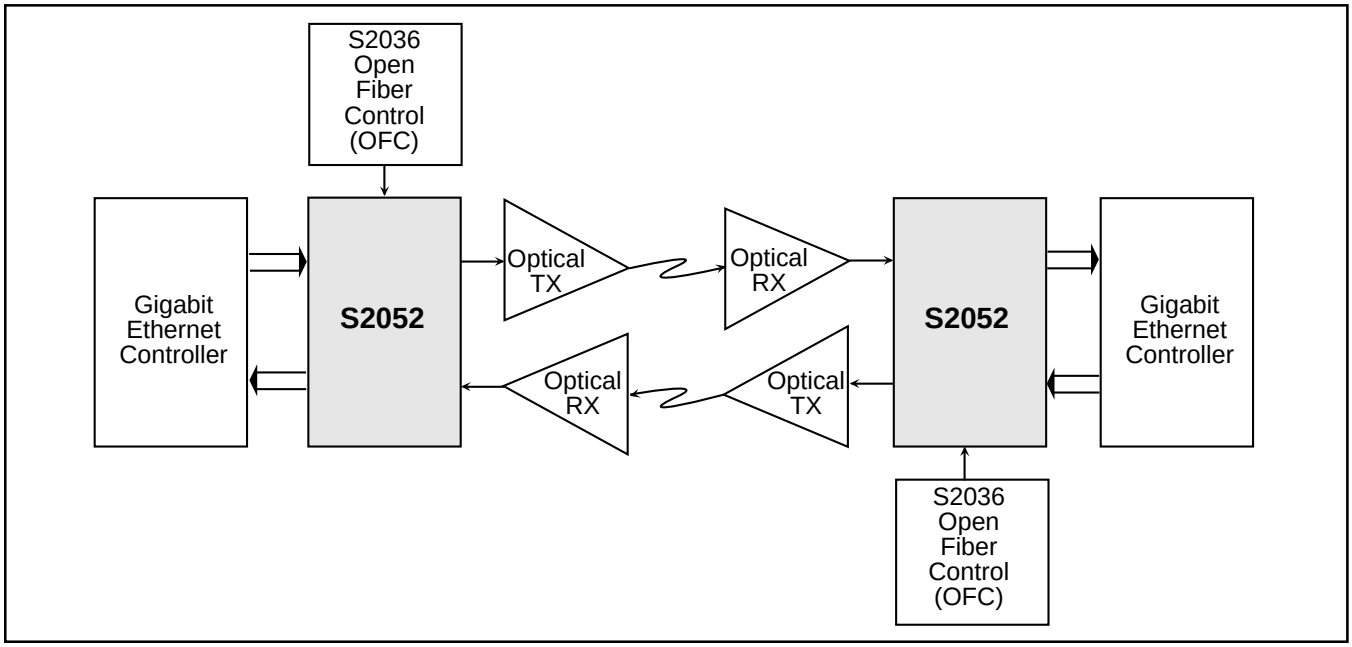
GENERAL DESCRIPTION

The S2052 transmitter and receiver chip is designed to perform high-speed serial data transmission over fiber optic or coaxial cable interfaces conforming to the requirements of the ANSI X3T11 Fibre Channel specification. The chip runs at 1250.0, and 1062.5 Mbit/s data rates with associated 10-bit data word.

The chip performs parallel-to-serial and serial-to-parallel conversion and framing for block-encoded data. The transmitter's on-chip PLL synthesizes the high-speed clock from a low-speed reference. The receiver's on-chip PLL synchronizes directly to incoming digital signal to receive the data stream. The transmitter and receiver each support differential PECL-compatible I/O for fiber optic component interfaces, to minimize crosstalk and maximize data integrity. Local loopback mode is provided for system diagnostics.

Figure 1 shows a typical configuration incorporating the chip, which is compatible with AMCC's S2036 Open Fiber Control (OFC) device.

Figure 1. System Block Diagram



S2052 OVERVIEW

The S2052 transmitter and receiver provide serialization and deserialization functions for block-encoded data to implement a Fibre Channel interface. Operation of the S2052 is straightforward, as depicted in Figure 2. The sequence of operations is as follows:

Transmitter
1. 10-bit parallel input
2. Parallel-to-serial conversion
3. Serial output

Receiver
1. Clock and data recovery from serial input
2. Serial-to-parallel conversion
3. Frame detection
4. 10-bit parallel output

The 10-bit parallel data handled by the S2052 device should be from a DC-balanced encoding scheme, such as the 8B/10B transmission code, in which information to be transmitted is encoded 8 bits at a time into 10-bit transmission characters[1], and be compliant with ANSI X3.230 FC-PH (Fibre Channel Physical and Signaling Interface).

Internal clocking and control functions are transparent to the user. Details of data timing can be seen in Figure 4. A block diagram showing the basic chip operation is shown in Figure 3.

Loopback

Local loopback is supported by the chip, and provides a capability for performing offline testing of the interface to ensure the integrity of the serial channel before enabling the transmission medium. It also allows for system diagnostics.

Figure 2. Interface Diagram

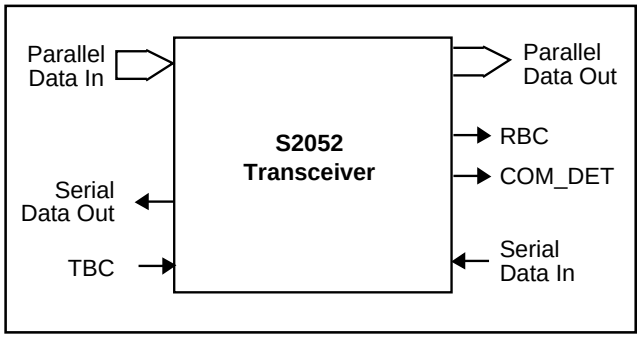
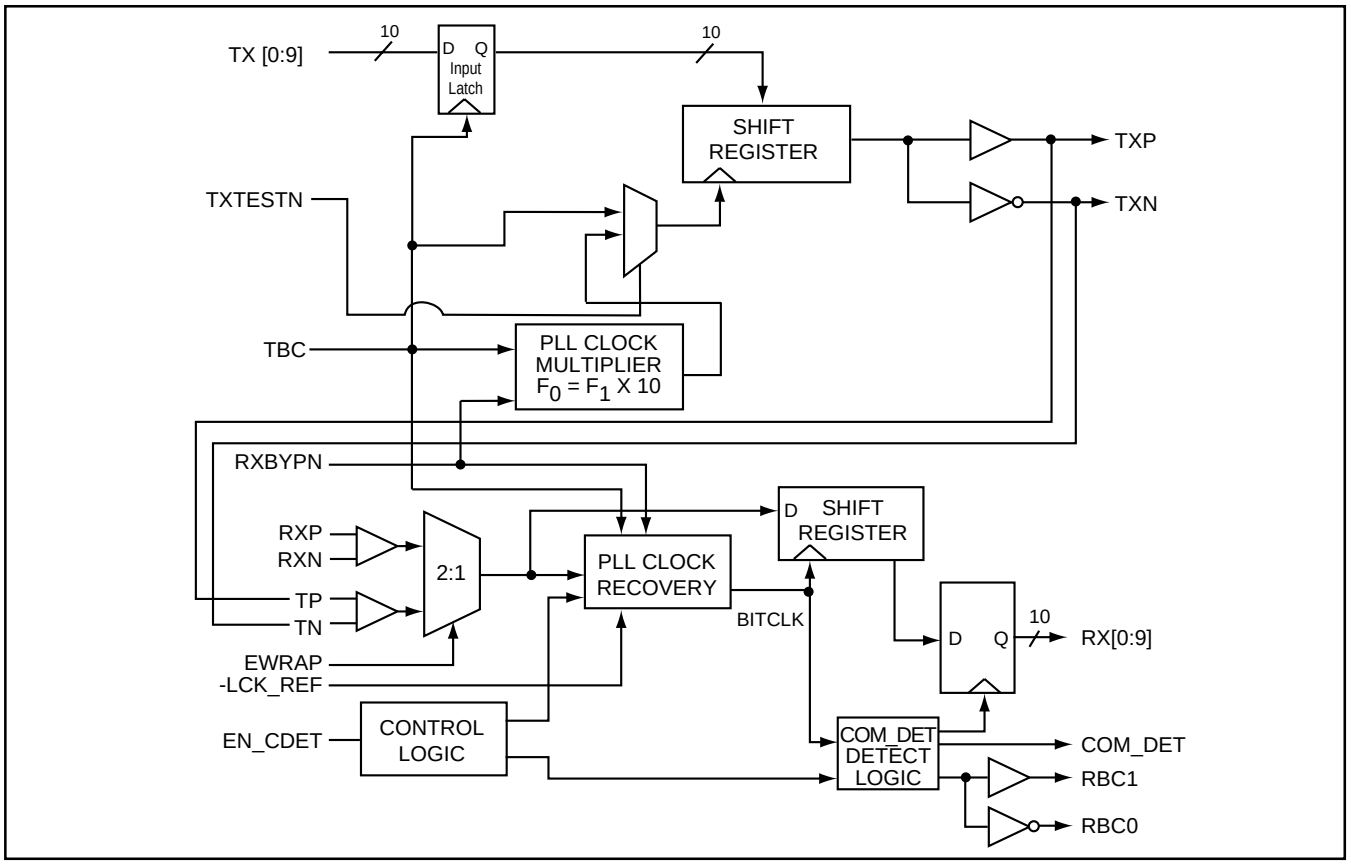


Figure 3. Functional Block Diagram



TRANSMITTER FUNCTIONAL DESCRIPTION

The S2052 transmitter accepts parallel input data and serializes it for transmission over fiber optic or coaxial cable media. The chip is fully compatible with the ANSI X3T11 Fibre Channel standard, and supports the Fibre Channel Gigabit Ethernet standard's data rates of 1250 and 1062 Mbit/sec. (See Figure 3.)

Parallel/Serial Conversion

The parallel-to-serial converter takes in 10-bit wide data from the input latch and converts it to a serial data stream. Parallel data is latched into the transmitter on the positive going edge of TBC. The data is then clocked synchronous to the clock synthesis unit serial clock into the serial output shift register. The shift register is clocked by the internally generated bit clock which is 10x of the TBC inputfrequency. D0 is transmitted first as described in annex N and Tables 22 and 23 of FC-PH. Table 1 shows the mapping of the parallel data to the 8B/10B codes.

Transmit Byte Clock

The transmit byte clock input (TBC) must be supplied with a clock source with 100 PPM tolerance to assure that the transmitted data meets the Fibre Channel frequency limits. The internal serial clock is frequency locked to the reference clock (125.00 and 106.25 MHz).

RECEIVER FUNCTIONAL DESCRIPTION

The S2052 receiver is designed to implement the ANSI X3T11 Fibre Channel specification and the IEEE 802.3Z Gigabit Ethernet receiver functions. A block diagram showing the basic chip function is provided in Figure 3.

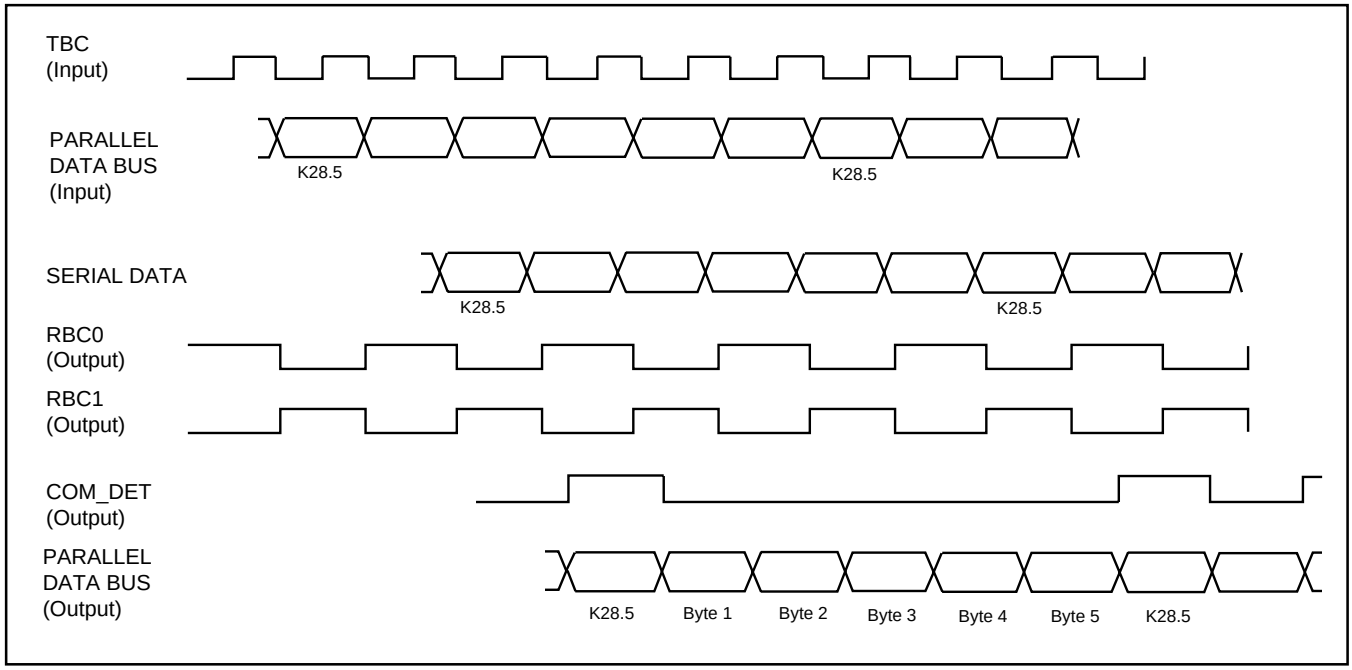
Whenever a signal is present, the S2052 attempts to achieve synchronization on both bit and transmission-word boundaries of the received encoded bit stream. Received data from the incoming bit stream is provided on the device's parallel data outputs.

The S2052 accepts serial encoded data from a fiber optic or coaxial cable interface. The serial input stream is the result of the serialization of 8B/10B encoded data by an FC compatible transmitter. Clock recovery is performed on-chip, with the output data presented to the Fibre Channel transmission layer as 10-bit parallel data.

Table 1. Data Mapping to 8b/10b Alphabetic Representation

	Data Byte									
TX[0:9] or RX[0:9]	0	1	2	3	4	5	6	7	8	9
8b/10b alphabetic representation	a	b	c	d	e	i	f	g	h	j

Figure 4. Functional Waveform (1250 and 1062.5 Mbit/sec)



1. A.X. Widmer and P.A. Franaszek, "A Byte-Oriented DC Balanced (0,4) 8B/10B Transmission Code," IBM Research Report RC 9391, May 1982.

Serial/Parallel Conversion

Serial data is received on the RX, RY pins. The PLL clock recovery circuit will lock to the data stream if the clock to be recovered is within ±100 PPM of the internally generated bit rate clock. The recovered clock is used to retime the input data stream. The data is then clocked into the serial to parallel output registers. Data is clocked out on the rising edge of RBC1 and RBC0. The parallel data out is 10 bits wide. The word clock (RBC1) is synchronized to the incoming data stream word boundary by the detection of the Fibre Channel Comma character, positive disparity (0011111XXXX), found in the K28.5 control character.

Transmit Byte Clock Input

The transmit byte clock input must be supplied with a TTL clock source at ±100 PPM tolerance.

Framing

The S2052 provides COM_DET character recognition and data word alignment of the TTL compatible output data bus. In systems where the COM_DET function is undesired, a LOW on the EN_CDET input disables the COM_DET function and the data will be “un-framed”.

When framing is disabled by low EN_CDET, the S2052 simply achieves bit synchronization within 250 bit times and begins to deliver parallel output data words whenever it has received full transmission words. No attempt is made to synchronize on any particular incoming character.

The COM_DET output signal will go high whenever a positive disparity comma character, found in the K28.5 control character, is present on the parallel data outputs. The COM_DET output signal will be low at all other times.

Lock Detect

The S2052 lock detect function monitors the state of the receiver phase-locked loop (PLL) clock recovery unit. The PLL will lock within 250 bit times after the start of receiving serial data inputs. If the serial data inputs have an instantaneous phase jump (from a serial switch, for example) the PLL will not indicate an out-of-lock state, but will recover the correct phase alignment within 50 to 250 bit times, depending on the input eye opening. (See Fig. 14). If a run length of 80-160 bits is exceeded, or if the input data rate varies by more than 1000 ppm compared to the reference clock, the loop will be declared out of lock. When lock is lost, the PLL will shift from the serial input data to the reference clock, so that the downstream clock will maintain the correct frequency.

In any transfer of PLL control from the serial data to the reference clock, the RBC1/RBC0 output remains phase continuous and glitch free, assuring the integrity of downstream clocking.

OTHER OPERATING MODES

Loopback

When local loopback is enabled, serial data from the transmitter is internally routed to the receiver, where the clock is extracted and the data is deserialized. The parallel data is then sent to the subsystem for verification. This loopback mode provides the capability to perform offline testing of the interface to guarantee the integrity of the serial channel before enabling the transmission medium. It also allows system diagnostics.

Operating Frequency Range

The S2052 is optimized for operation at 1250 and 1062 Mbit/s. Operation at other rates is possible if the rate falls between the nominal rates. REFCLK must be selected to be within 100 ppm of the desired byte or word clock rate.

S2052 Transmitter Pin Assignment and Descriptions

Pin Name	Level	I/O	Pin #	Description
TX9 TX8 TX7 TX6 TX5 TX4 TX3 TX2 TX1 TX0	TTL	I	13 12 11 9 8 7 6 4 3 2	Transmit data. Parallel data on this bus is clocked in on the rising edge of TBC. TX0 is transmitted first.
TBC	TTL	I	22	Reference clock and transmit byte clock, a crystal-controlled reference clock for the PLL clock multiplier. The frequency of TBC is the bit rate divided by 10.
TXTESTN	TTL	I	10	When LOW, TBC replaces internal TX bit clock to facilitate factory testing. When HIGH, the TX PLL will lock to the TBC input.
TXP TXN	Diff. PECL	O	62 61	Differential PECL outputs that send out the serial transmitter data and drive 75Ω or 50Ω termination to Vcc–2V. TXP is the positive output, and TXN is the negative output.

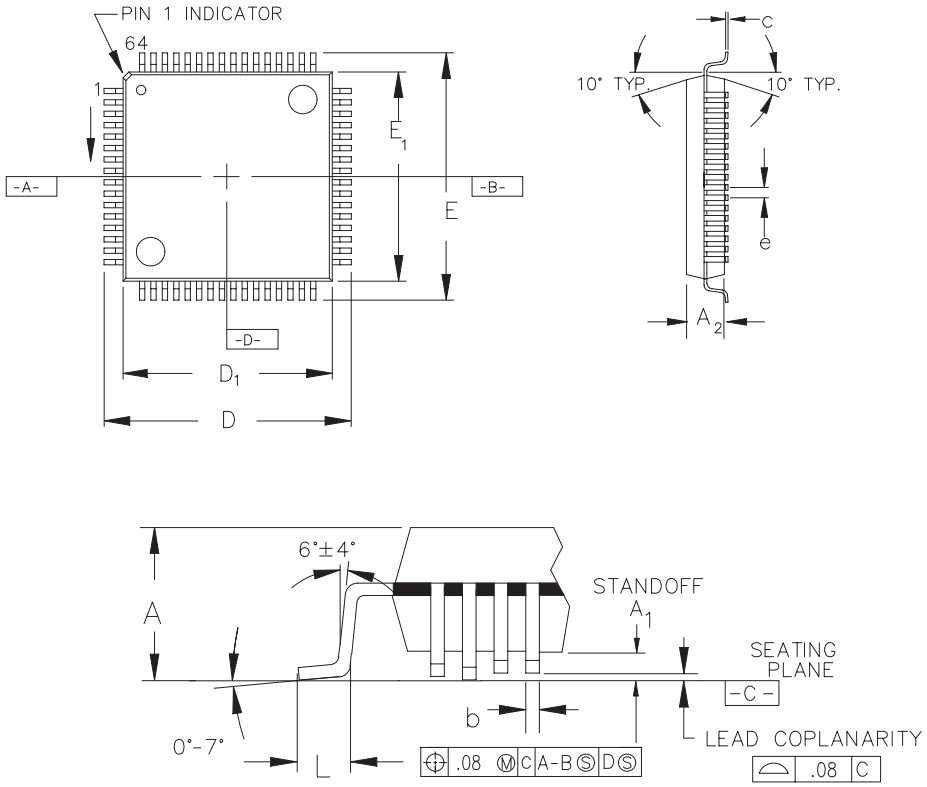
S2052 Receiver Pin Assignment and Descriptions

Pin Name	Level	I/O	Pin #	Description
RX9 RX8 RX7 RX6 RX5 RX4 RX3 RX2 RX1 RX0	TTL	O	34 35 36 38 39 40 41 43 44 45	Receive data outputs. Parallel data on this bus is valid on the rising edge of RBC0 and RBC1. RX0 is the first bit received.
RBC1 RBC0	Diff. TTL	O	30 31	Receive clock. Parallel data is valid on the rising edge of RBC0 and RBC1 (see timing diagram in Figure 8). After a sync word is detected, the period of the current RBC1 and RBC0 is stretched to align with the word boundary.
EN_CDET	TTL	I	24	Enable comma detect. When High, enables sync detection. Detection of the 7-bit comma + character sync pattern, RX(0-9) = (K28.5:0011111XXX), will enable the word boundary for the data to follow. When Low, data is treated as unframed data.
RXP RXN	Diff. LVPECL	I	54 52	(Externally capacitively coupled.) Differential LVPECL received serial data inputs. RXP is the positive input, and RXN is the negative input. Internally biased.
RXBYPN	TTL	I	5	When Low, TBC replaces internal RX bit clock to facilitate factory testing.
–LCK_REF	Level Static	I	27	Multi-level Static Lock to reference input. When Low, the RX PLL will lock to the TBC input. When High, the RX PLL will lock to the incoming data. When Open (not connected), the RX will be held in reset.
COM_DET	TTL	O	47	Comma detect. Upon detection of a valid sync symbol, this output goes high for one RBC1 period. When sync is active, the sync character shall be present on the parallel data bus bits RX0–RX9.

S2052 Common Pin Assignment and Descriptions

Pin Name	Level	I/O	Pin #	Description
EWRAP	TTL	I	19	Enable Wrap input. When High, selects the transmitter serial output data to be routed to the receiver. When Open (not connected), the transmitter is held in the reset state and RXP/N is selected. When Low, selects RXP and RXN (normal operation). TXP, TXN are static when EWRAP is High.
ECLVCC	+3.3V	–	20, 23	Core +3.3V
TTLGND	GND	–	32, 46	TTL Ground
TTLVCC	3.3V	–	37, 42	TTL Power Supply (3.3V)
ECLIOVCC	3.3V	–	55, 60, 63	PECL I/O Power Supply (3.3V)
ECLIOVEE	GND	–	56, 64	PECL I/O Ground
AVCC	3.3V	–	18, 50	Analog Power Supply (3.3V)
AVEE	GND	–	15, 51	Analog Ground
ECLVEE	GND	–	21, 25, 58	Core Ground
GND	GND	–	1, 14	These pins require connection to Ground.
NC	–	–	16, 17, 26, 28, 29, 33, 48, 49, 53, 57, 59	No Connection

Figure 5. 64 PQFP (10mm x 10mm) Package



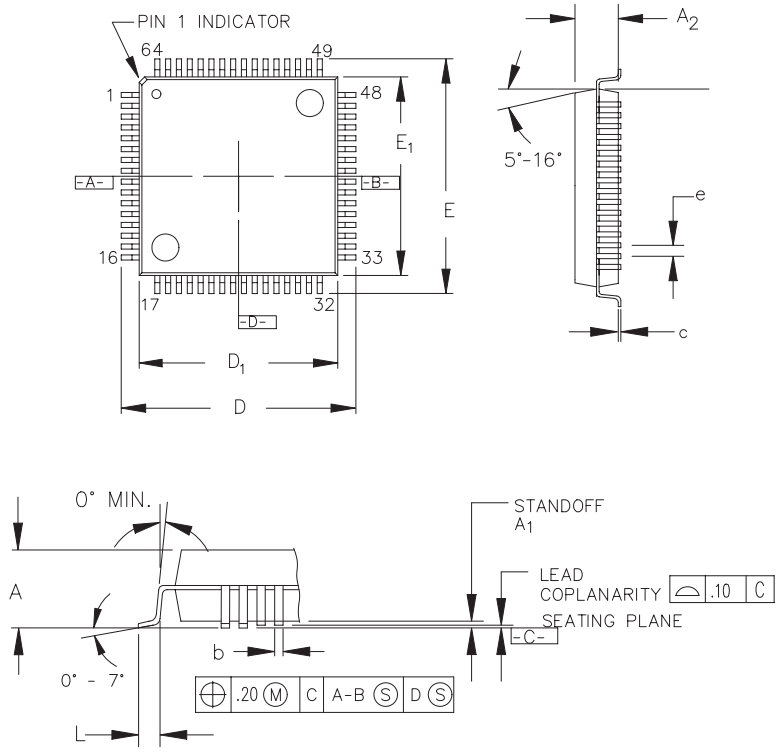
DIMENSIONS (are in millimeters)

UNIT	A	A_1	A_2	D	D_1	E	E_1	L	e	b	c
MIN		0.25	1.95	13.00	9.90	13.00	9.90	0.78	0.50 BSC.	0.17	
NOM			2.00	13.20	10.00	13.20	10.00	0.88		0.22	
MAX	2.45	0.50	2.10	13.40	10.10	13.40	10.10	1.03		0.27	0.17

Thermal Management

Device	Θja (Still Air)
S2052C (10 x 10)	52° C/W

Figure 6. 64 PQFP (14mm x 14mm) Package



DIMENSIONS (are in millimeters)

UNIT	A	A_1	A_2	D	D_1	E	E_1	L	b	e	c
MIN			1.95	16.95	13.90	16.95	13.90	0.78	0.30	0.80 BSC.	
NOM			2.00	17.20	14.00	17.20	14.00	0.88	0.35		
MAX	2.35	0.25	2.10	17.45	14.10	17.45	14.10	1.03	0.45		0.17

Thermal Management

Device	Θja (Still Air)
S2052B (14 x 14)	45° C/W

Absolute Maximum Ratings

PARAMETER	MIN	TYP	MAX	UNIT
Case Temperature under Bias	-55		125	°C
Junction Temperature under Bias	-55		150	°C
Storage Temperature	-65		150	°C
Voltage on VCC with Repect to GND	-0.5		+7.0	V
Voltage on any TTL Input Pin except Tx [0:9]	-0.5		3.47	V
Voltage on TTL input pin TX [0:9]			+5.5	V
Voltage on any PECL Input Pin	0		VCC	V
TTL Output Sink Current			8	mA
TTL Output Source Current			8	mA
High Speed PECL Output Source Current			50	mA
Static Discharge Voltage		500		V

Recommended Operating Conditions

PARAMETER	MIN	TYP	MAX	UNIT
Ambient Temperature under Bias	0		70	°C
Junction Temperature under Bias			130	°C
Voltage on TTLVCC, ECLVCC, ECLIOVCC, and AVCC with respect to GND/VEE	3.13	3.3	3.47	V
Voltage on TTL Input Pin except TX [0:9]	0		3.47	V
Voltage on any PECL Input Pin	VCC -2.0V		VCC	V
Voltage on TTL data TX [0:9]	0		5.0	

Reference Clock Requirements

Parameters	Description	Min	Max	Units	Conditions
FT	Frequency Tolerance	-100	+100	ppm	—
TD_{1-2}	Symmetry	40	60	%	Duty Cycle at 50% pt.
T_{RCR}, T_{RCF}	REFCLK Rise and Fall Time	—	2	ns	20 – 80%
—	Random Jitter		100	ps	Peak-to-Peak

Table 2. S2052 DC Characteristics

Parameters	Description	Min	Typ	Max	Units	Conditions
V_{OH}	Output HIGH Voltage (TTL)	2.2	2.5	VCC	V	V_{CC} = min, I_{OH} = -400 µA
V_{OL}	Output LOW Voltage (TTL)	GND	.025	0.5	V	V_{CC} = max, I_{OL} = 1 mA
V_{IH}	Input HIGH Voltage (TTL)	2.0	—	—	V	$I_H \leq$ 1mA at V_{IH} = 5.5V
V_{IL}	Input LOW Voltage (TTL)	GND	—	0.8	V	—
I_{IH}	Input HIGH Current (TTL)	—	—	40	µA	V_{IN} = 2.4V, V_{CC} = max
I_{IL}	Input LOW Current (TTL)	—	—	600	µA	V_{IN} = 0.4V, V_{CC} = max
I_{CC}	Supply Current		310	340	mA	Outputs open, V_{CC} = V_{CC} max SQ pattern
P_D	Power Dissipation		1.0	1.2	W	Outputs open, V_{CC} = V_{CC} max SQ pattern
V_{DIFF}	Min. differential input voltage swing for differential PECL inputs	100		1300	mV	
ΔV_{OUT}	Serial Output Voltage Swing	600	—	1600	mV	50Ω to V_{CC} -2.0V
C_{in}	Input capacitance	—		4	PF	

Table 3. S2052 Performance Summary

Parameter	S2052		Units
Operating Frequency *	1250	1062.5	Mbit/s
Serial clock period	.800	.941	ns
Byte clock period	8.00	9.41	ns
Acquisition Time	250	250	ns
Reference clock	125.0	106.25	MHz
Word width	10	10	Bits

* ±10% lock range, nominal frequency is per FC-PH standard.

Table 4. S2052 Transmitter Timing

Parameters	Description	Min	Max	Units	Conditions
T_1	Data setup w.r.t. ↑REFCLK	2	—	ns	See note.
T_2	Data hold w.r.t. ↑REFCLK	1.0	—	ns	—
T_{SDR} , T_{SDF}	Serial data rise and fall	—	300	ps	20% to 80%, tested on a sample basis.
Transmitter Output Jitter Allocation					
T_J	Serial data output total jitter (RMS)	—	192	ps	Peak-to-peak, tested on a sample basis. Measured with ± K28.5 or 2^7-1 pattern.
T_{DJ}	Serial data output deterministic jitter (p-p)	—	80	ps	Peak-to-peak, tested on a sample basis. Measured with K28.5± @ 1.25 GHz.

Note: All AC measurements are made from the reference voltage level of the clock (1.4V) to the valid input or output data levels (.8V or 2.0V).

Table 5. S2052 Receiver Timing

Parameters	Description	Min	Max	Units	Conditions
T_3	RBC0 to RBC1 skew	—	1	ns	Tested on a sample basis.
T_4	Data setup w.r.t. RBC0, RBC1	3.0		ns	1.0625 GHz Mode
T_5	Data hold w.r.t. RBC0, RBC1	1.5		ns	1.0625 GHz Mode
T_6	Data setup w.r.t. RBC0, RBC1	2.5		ns	1.250 GHz Mode
T_7	Data hold w.r.t. RBC0, RBC1	1.5		ns	1.250 GHz Mode
T_{RCR} , T_{RCF}	RBC0, RBC1 rise and fall time	—	3.0	ns	Measured from .8V to 2.0V.
T_{DR} , T_{DF}	Data Output rise and fall time	—	3.0	ns	Measured from .8V to 2.0V.
T_{SDR} , T_{SDF}	Serial data input rise and fall	—	300	ps	20% to 80%. (See Figure 10.)
T_{LOCK}	Data acquisition lock time @ <1.0625Gb/s	—	2.4	µs	8B/10B IDLE pattern sample basis.
Duty Cycle	RBC0/RBC1 Duty Cycle	40%	60%		
Input Jitter Tolerance	Input data eye opening allocation at receiver input for BER ≤1E–12	24%	—	bit time	As specified in IEEE 803.3z.

Note: All TTL/CMOS AC measurements are assumed to have the output load of 10pF.

Figure 7. Transmitter Timing Diagram

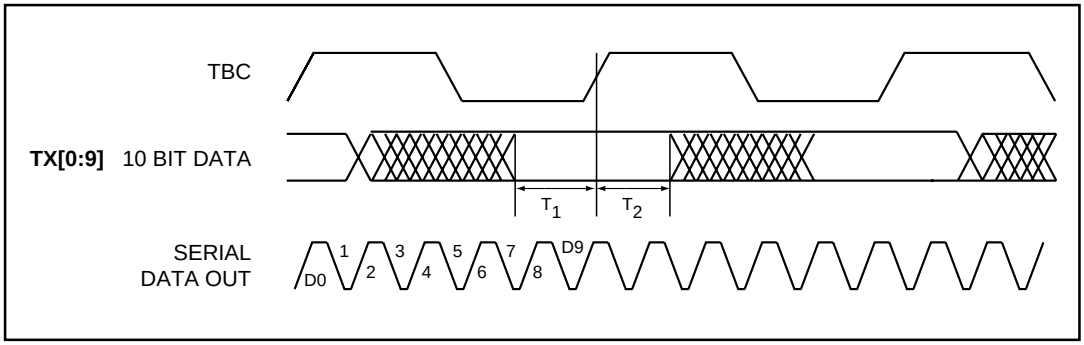


Figure 8. Receiver Timing Diagram (1062.5 Mbits/sec mode)

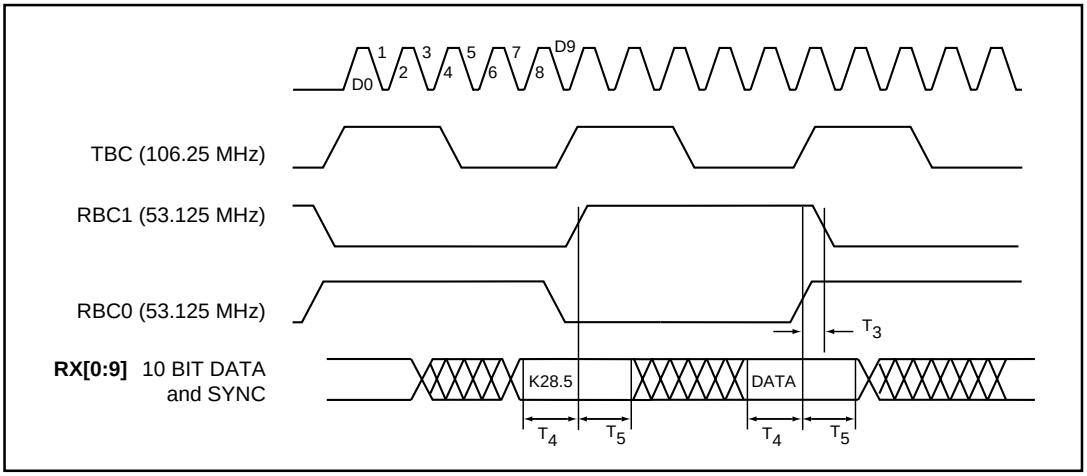


Figure 9. Receiver Timing Diagram (1250 Mbits/sec mode)

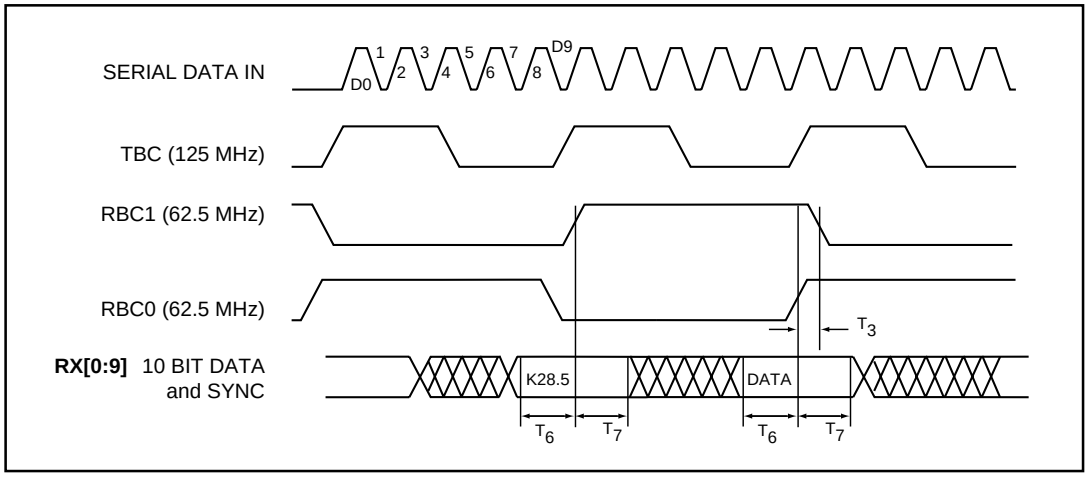


Figure 10. Serial Input Rise and Fall Time

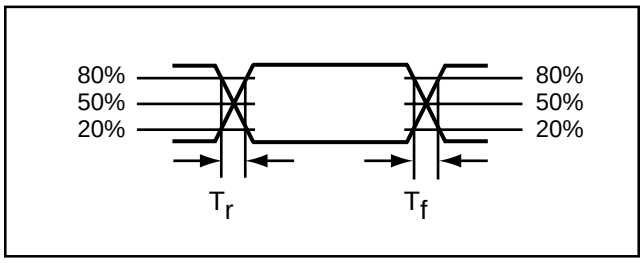


Figure 11. Serial Output Load

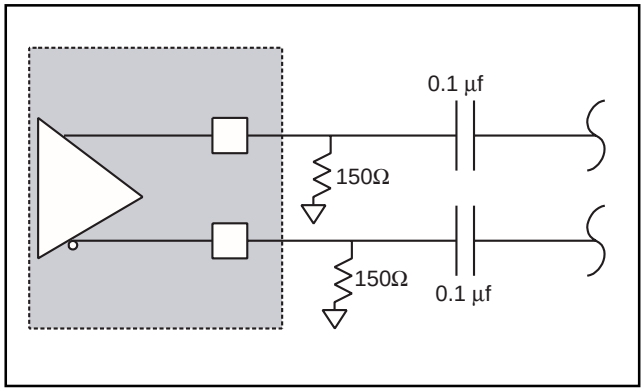


Figure 12. TTL Input and Output Rise and Fall Time

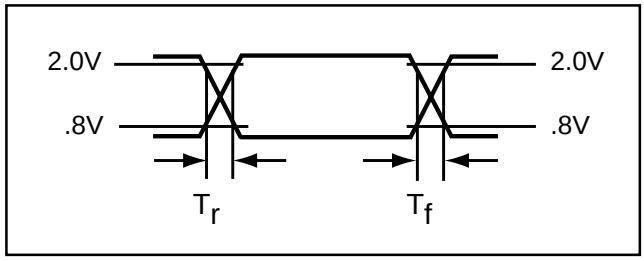
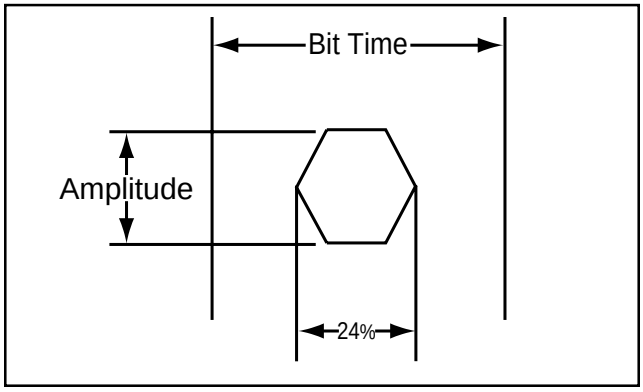


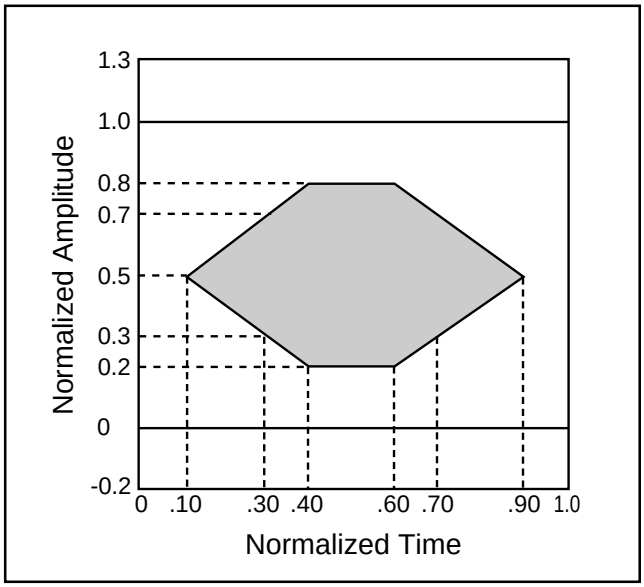
Figure 13. Receiver Input Eye Diagram Jitter Mask



ACQUISITION TIME

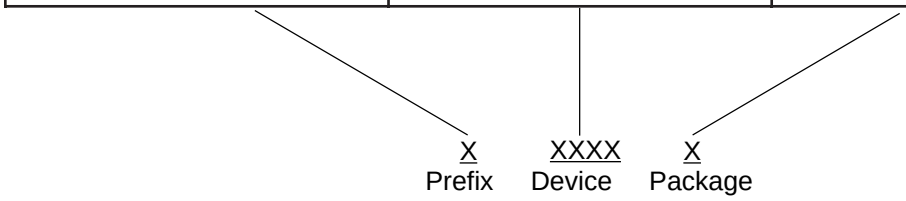
With the input eye diagram shown in Figure 14, the S2052 will recover data with a 10^{-9} BER within 50 bit times after an instantaneous phase shift of the incoming data.

Figure 14. Acquisition Time Eye Diagram



Ordering Information

PREFIX	DEVICE	PACKAGE
S – Integrated Circuit	2052	B – 64 PQFP (14mm) C – 64 PQFP (10mm)



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